

X13 Hyper-E

Best-in-class Performance and Flexibility for Edge Data Centers



Flagship performance in a short-depth form factors

- Short depth form factor (574mm/22.6") for space-constrained environments
- Enhanced serviceability in the field with front I/O
- Up to 3 PCIe 5.0 x16 double-width or 6 PCIe 5.0 x16 single-width slots
- AC and DC power supply options

Short-depth, Maximum Performance

Hyper-E brings the performance and flexibility of Supermicro's flagship Hyper series to the Edge with short-depth form factors designed for Edge data center and telco deployments. Telco-optimized configurations are NEBS Level 3 certified and feature optional DC power supplies on selected models.

Optimized for 5G and Telco Applications

The compact form factor, many expansion options, and powerful compute make the Hyper-E ideal for 5G, telco and intelligent edge applications including Cloud, Network Function Virtualization, AI Edge Inferencing, Telco Data Center and 5G Core/Edge. All I/O and expansion slots are front-accessible for easy servicing in space-constrained environments, while maintenance-friendly design innovations eliminate the need for tools when servicing, simplifying rollout and installation.

AI at the Edge

The Hyper-E is able to support up to 3 double-width GPU/FPGA cards, enabling it to support demanding AI workloads, such as ML training and data inferencing. Combined with its compact form factor and front access design, this make the Hyper-E a powerful platform for intelligent solutions at the edge.

Powered by 4th Gen Intel Xeon Scalable Processors

Get data-center power at the Edge with dual 4th Gen Intel Xeon Scalable Processors up to 350W TDP each. The new processors are available in Edge-optimized SKUs which feature the built-in Intel vRAN Boost accelerator which can reduce power consumption by up to 20% on vRAN workloads.



Hyper-E	SYS-221HE-FTNR	SYS-221HE-FTNRD
Processor Support	Dual Socket E (LGA-4677) 4th Gen Intel® Xeon® Scalable processors [†]	Dual Socket E (LGA-4677) 4th Gen Intel® Xeon® Scalable processors [†]
Oustanding Features	Tool-less system design for east maintenance Storage configurations up to 6x 2.5" hot-swap NVMe/SATA drive bays Flexible networking options with 2 AIOM networking slots (OCP NIC 3.0 compatible)	Tool-less system design for east maintenance Storage configurations up to 6x 2.5" hot-swap NVMe/SATA drive bays Flexible networking options with 2 AIOM networking slots (OCP NIC 3.0 compatible)
Memory Slots & Capacity	32 DIMM slots Up to 8TB: 32x 256GB DDR5 ECC RDIMM/RDIMM	32 DIMM slots Up to 8TB: 32x 256GB DDR5 ECC RDIMM/RDIMM
Network Connectivity	2x 100GbE QSFP28 with Broadcom® BCM57508 (optional) 2x 100GbE QSFP28 with Intel® E810-CAM2 (optional) 2x 100GbE QSFP28 with Mellanox® CX-6 DX (optional) 2x 25GbE SFP28 with Broadcom® BCM57414 (optional) 4x 10GbE RJ45 with Intel® X550 (optional) 4x 10GbE SFP+ with Intel® X710-BM2 (optional) via AIOM 1 RJ45 Dedicated BMC LAN port 2 USB 2.0 port(s) (2 front) 1 VGA port(s)	2x 100GbE QSFP28 with Broadcom® BCM57508 (optional) 2x 100GbE QSFP28 with Intel® E810-CAM2 (optional) 2x 100GbE QSFP28 with Mellanox® CX-6 DX (optional) 2x 25GbE SFP28 with Broadcom® BCM57414 (optional) 4x 10GbE RJ45 with Intel® X550 (optional) 4x 10GbE SFP+ with Intel® X710-BM2 (optional) via AIOM 1 RJ45 Dedicated BMC LAN port 2 USB 2.0 port(s) (2 front) 1 VGA port(s)
MotherBoard	X13DEM	X13DEM
Form Factor	2U Rackmount Enclosure: 436.88 x 88.9 x 574mm (17.2" x 3.5" x 22.6") Package: 598 x 247 x 938mm (23.5" x 9.7" x 36.9")	2U Rackmount Enclosure: 436.88 x 88.9 x 574mm (17.2" x 3.5" x 22.6") Package: 598 x 247 x 938mm (23.5" x 9.7" x 36.9")
Expansion Slots	Configurable PCIe slot options up to 8 PCIe 5.0 x8 (6 FHFL+ 2 FHHL) or 4 PCIe 5.0 x16 (3 FHFL + FHHL)	Configurable PCIe slot options up to 8 PCIe 5.0 x8 (6 FHFL+ 2 FHHL) or 4 PCIe 5.0 x16 (3 FHFL + FHHL)
Drive Bays	6x 2.5" hot-swap NVMe/SATA drive bays; 6x 2.5" NVMe hybrid; Optional RAID support via RAID Controller AOC	6x 2.5" hot-swap NVMe/SATA drive bays; 6x 2.5" NVMe hybrid; Optional RAID support via RAID Controller AOC
Shared Power & Cooling	Redundant 2000W Titanium level (96%) 6x heavy duty fan(s)	2x 1300W -48Vdc single output 6x heavy duty fan(s)

[†] Supports up to 350W TDP CPUs (Aircooled). CPUs with high TDP supported under specific conditions. Contact Technical Support for details.